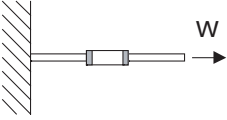
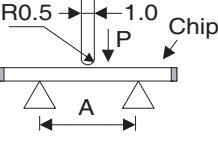


■ PERFORMANCE TESTS

TEST	SPECIFICATION	TEST CONDITION		
Solderability	* More than 90% of the terminal electrode will be covered with fresh solder.	Solder Temperature: 240 ± 5°C		
Soldering Heat Resistance	* The chip will not crack. * More than 75% of the terminal electrode will be covered with solder.	Solder Temperature: 255 ± 5°C Dip Time: 3 ± 1 Seconds		
Terminal Strength	* The terminal electrode shall not break and the ferrite will not be damaged. 	TYPE	KGF	Time(sec)
		GMLB-160808	0.6	30 ± 5
		GMLB-201209		
		GMLB-321611	1.0	
		GMLB-321616		
		GMLB-322513		
		GMLB-451616		
GMLB-453215	1.5			
Bending Strength	* There will be no mechanical damage. * The ferrite will not be damaged. 	TYPE	A(mm)	KGF
		GMLB-100505	0.4	0.2
		GMLB-160808	1.0	1.0
		GMLB-201209	1.4	
		GMLB-321611	2.0	2.0
		GMLB-321616		
		GMLB-451616	2.5	2.5
GMLB-453215	2.7			

■ CLIMATIC TESTS

TEST	SPECIFICATION	TEST CONDITION
Thermal Shock (Temperature Cycle)	* Impedance will be within 20% of the initial value.	* Temperature cycles -25°C then +125°C for 30 minutes each. Total Cycles: 100
Humidity Resistance		* Temperature: 60°C * Humidity: 90% RH * Applied Current: Rated Current * Time=1000±12 hours
High Temperature Resistance		* Temperature: 80°C * Applied Current: Rated Current * Time=1000±12 hours

1. Operating Temperature Range: -55°C TO +125°C

2. Storage Condition: The temperature should be within -40 TO +85°C and humidity should be less than 75%RH. The product should be used within 6 months from the time of delivery.